Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

Employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Optimized for Low Leakage Current
- NRVBA Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL94, V_O at 1/8"
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- Available in 12 mm Tape, 5000 Units per 13 inch Reel
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V) Human Body Model, 3B (>8000 V)
- Marking: B1E2



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SCHOTTKY BARRIER RECTIFIER 1 AMPERE 20 VOLTS

MARKING DIAGRAM



SMA CASE 403D



B1E2 = Specific Device Code A = Assembly Location**

Y = Year
WW = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|---------------|------------------|-----------------------|
| MBRA120ET3G | SMA (Pb-Free) | 5000 / Tape & Reel |
| NRVBA120ET3G* | SMA (Pb-Free) | 5000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|--|-------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 20 | V |
| Average Rectified Forward Current (At Rated V_R , $T_C = 125^{\circ}C$) | I _O | 1.0 | Α |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I _{FSM} | 40 | Α |
| Storage Temperature | T _{stg} | -55 to +150 | °C |
| Operating Junction Temperature | TJ | -55 to +150 | °C |
| Voltage Rate of Change (Rated V_R , $T_J = 25$ °C) | dv/dt | 10,000 | V/μs |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | 5 mm x 5 mm (Note 2) | 1 Inch x 1/2 inch (Note 3) | Unit |
|--|-----------------------------|-------------------------|-------------------------------|------|
| Thermal Resistance – Junction-to-Lead Thermal Resistance – Junction-to-Ambient | $R_{	hetaJL}$ $R_{	hetaJA}$ | 34 138 | 20 77 | °C/W |

ELECTRICAL CHARACTERISTICS

| Maximum Instantaneous Forward Voltage (Note 1), See Figure 2 | V _F | T _J = 25°C | T _J = 100°C | V |
|--|----------------|-------------------------|-------------------------|----|
| (I _F = 0.1 A) (I _F = 1.0 A) (I _F = 2.0 A) | | 0.455 0.530 0.595 | 0.360 0.455 0.540 | |
| Maximum Instantaneous Reverse Current, See Figure 4 | I _R | T _J = 25°C | T _J = 100°C | μΑ |
| (V _R = 20 V) (V _R = 10 V) (V _R = 5.0 V) | | 10 1.0 0.5 | 1600 500 300 | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2%.

- 2. Mounted on a Pad Size of 5 mm x 5 mm, PC Board FR4 (2 pads).
- 3. Mounted on a Pad Size of 1 inch x 1/2 inch, PC Board FR4 (2 pads).

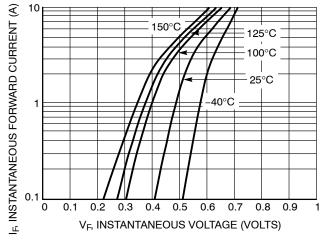


Figure 1. Typical Forward Voltage

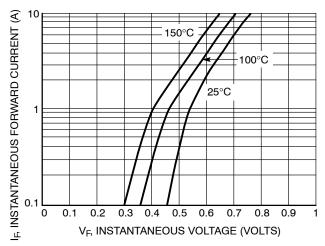


Figure 2. Maximum Forward Voltage

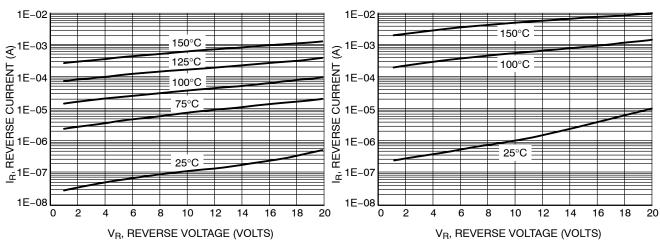


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

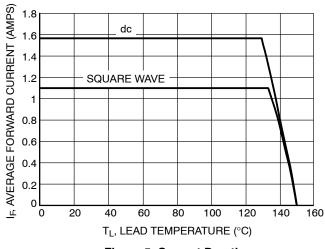


Figure 5. Current Derating

Figure 6. Forward Power Dissipation

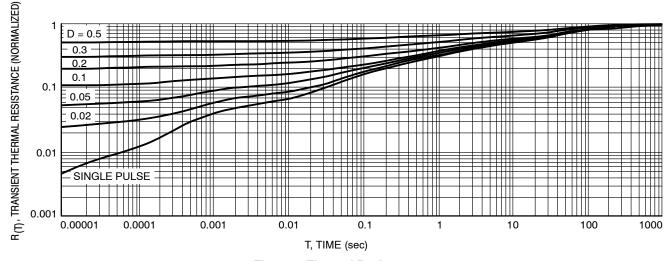


Figure 7. Thermal Resistance

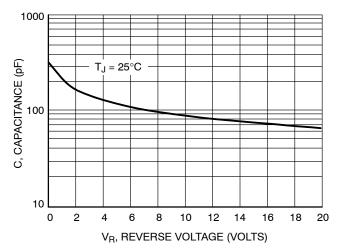
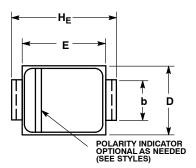


Figure 8. Typical Junction Capacitance

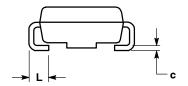
PACKAGE DIMENSIONS

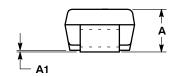
SMA CASE 403D **ISSUE H**



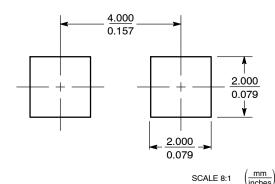
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH. 2
- DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 1.97 | 2.10 | 2.20 | 0.078 | 0.083 | 0.087 |
| A1 | 0.05 | 0.10 | 0.20 | 0.002 | 0.004 | 0.008 |
| b | 1.27 | 1.45 | 1.63 | 0.050 | 0.057 | 0.064 |
| С | 0.15 | 0.28 | 0.41 | 0.006 | 0.011 | 0.016 |
| D | 2.29 | 2.60 | 2.92 | 0.090 | 0.103 | 0.115 |
| E | 4.06 | 4.32 | 4.57 | 0.160 | 0.170 | 0.180 |
| HE | 4.83 | 5.21 | 5.59 | 0.190 | 0.205 | 0.220 |
| L | 0.76 | 1.14 | 1.52 | 0.030 | 0.045 | 0.060 |





SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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